

**REUSABLE THERMOPLASTIC THERMAL INTERFACE MATERIALS AND
METHODS FOR ESTABLISHING THERMAL JOINTS BETWEEN HEAT SOURCES
AND HEAT DISSIPATING/REMOVAL STRUCTURES**

ABSTRACT

According to various aspects, exemplary embodiments are disclosed of thermal interface materials, electronic devices, and methods for establishing thermal joints between heat sources and heat dissipating and/or heat removal structures, devices, or components. In exemplary embodiments, a thermal interface material is configured to have an inverse tan delta of at least 1.1 from about room temperature to about 125 °C and/or a bond line thickness predetermined to be at least 1.1 times greater than a largest filler particle size of the thermal interface material.

Figure 1